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With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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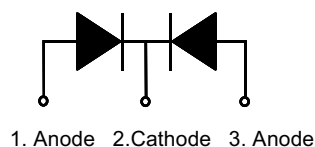
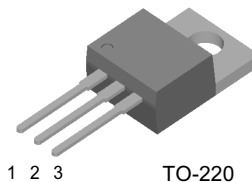
## FFP15U20DN

### Features

- Ultrafast with soft recovery.
- Low forward voltage.

### Applications

- Power switching circuits.
- Output rectifiers.
- Freewheeling diodes.
- Switching mode power supply.



## FAST RECOVERY POWER RECTIFIER

### Absolute Maximum Ratings (per diode) $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
$V_{RRM}$	Peak Repetitive Reverse Voltage	200	V
$I_{F(AV)}$	Average Rectified Forward Current @ $T_C = 100^\circ\text{C}$	15	A
$I_{FSM}$	Non-repetitive Peak Surge Current 60Hz Single Half-Sine Wave	150	A
$T_J, T_{STG}$	Operating Junction and Storage Temperature	- 65 to +150	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	Value	Units
$R_{\theta JC}$	Maximum Thermal Resistance, Junction to Case	3.1	$^\circ\text{C}/\text{W}$

### Electrical Characteristics (per diode) $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Units	
$V_{FM}^*$	Maximum Instantaneous Forward Voltage $I_F = 15\text{A}$	$T_C = 25^\circ\text{C}$	-	-	1.2	V
		$T_C = 100^\circ\text{C}$	-	-	1.0	
$I_{RM}^*$	Maximum Instantaneous Reverse Current @ rated $V_R$	$T_C = 25^\circ\text{C}$	-	-	15	$\mu\text{A}$
		$T_C = 100^\circ\text{C}$	-	-	150	
$t_{rr}$	Maximum Reverse Recovery Time	-	-	40	ns	
$I_{rr}$	Maximum Reverse Recovery Current	-	-	3.5	A	
$Q_{rr}$	Maximum Reverse Recovery Charge ( $I_F = 15\text{A}$ , $di/dt = 200\text{A}/\mu\text{s}$ )	-	-	70	nC	
$W_{AVL}$	Avalanche Energy	0.5	-	-	mJ	

\* Pulse Test: Pulse Width=300 $\mu\text{s}$ , Duty Cycle=2%

# Typical Characteristics

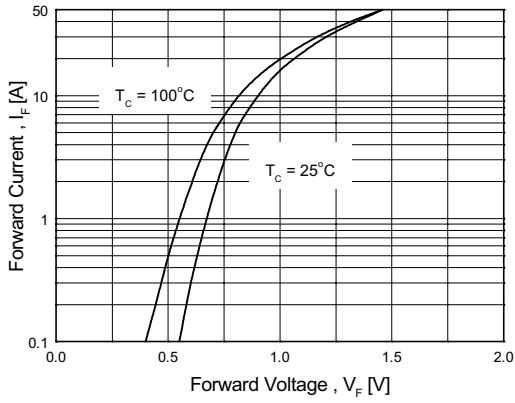


Figure 1. Typical Forward Voltage Drop vs. Forward Current

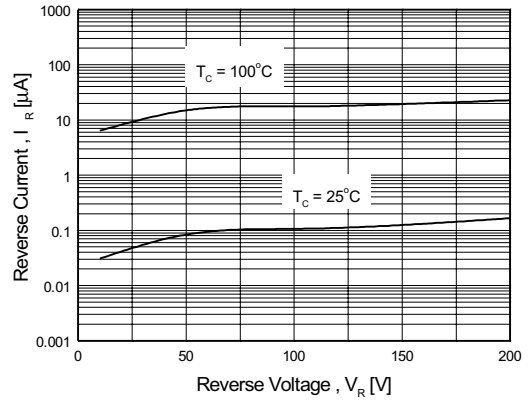


Figure 2. Typical Reverse Current vs. Reverse Voltage

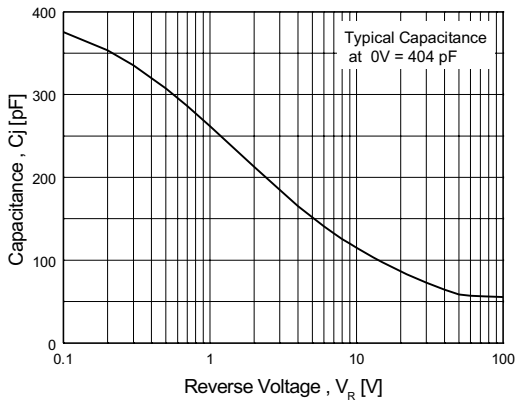


Figure 3. Typical Junction Capacitance

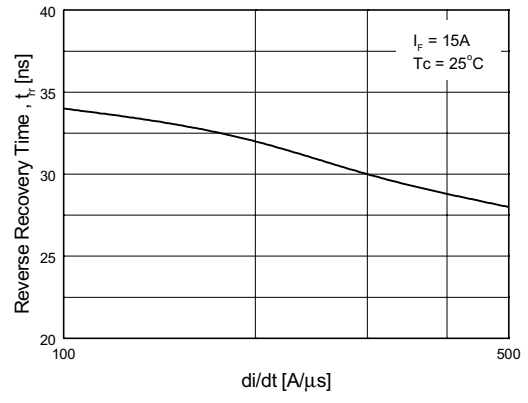


Figure 4. Typical Reverse Recovery Time vs. di/dt

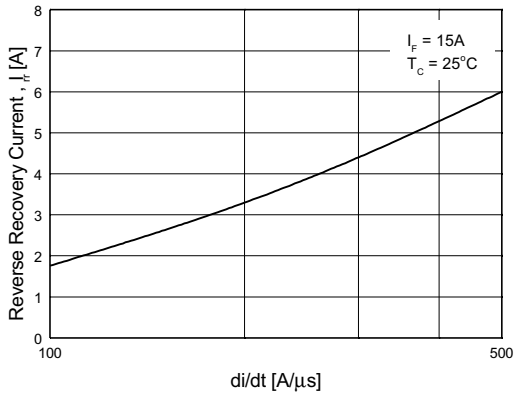


Figure 5. Typical Reverse Recovery Current vs. di/dt

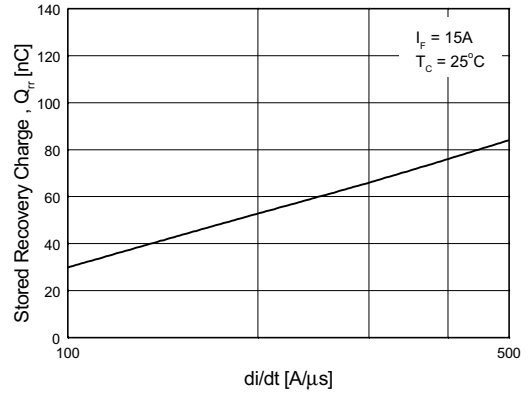
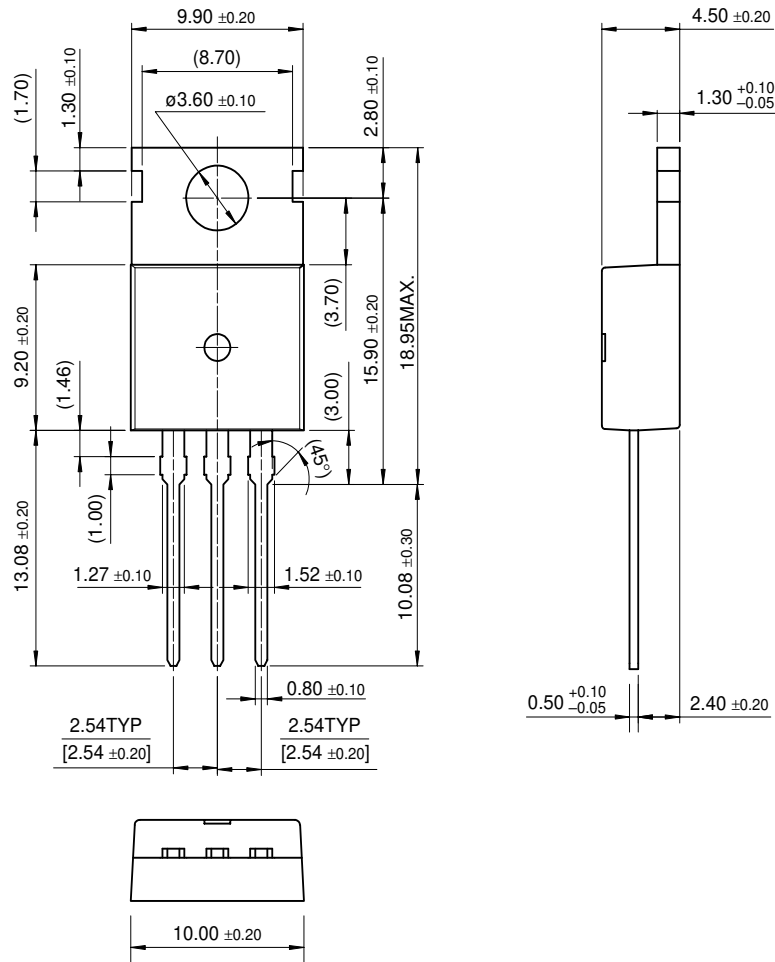


Figure 6. Typical Stored Charge vs. di/dt

# Package Dimensions

## TO-220

FFP15U20DN



Dimensions in Millimeters

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